

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of: Ponnekanti et al.

Serial No.: Unknown

Filed: Herewith

For: A Process And An Integrated Tool
For Low K Dielectric Deposition Including
A Pecvd Capping Module

Group Art Unit: Unknown

Examiner: Unknown

Assistant Commissioner for Patents
Washington, D.C. 20231

CERTIFICATE OF MAILING 37 C.F.R. 1.8	
I hereby certify that this correspondence is being deposited on <u>2/10/2000</u> 2000, with the U. S. Postal Service as First Class	
Mail in an envelope addressed to: Assistant Commissioner for Patents, Washington, D.C. 20231.	
Date <u>2/10/2000</u>	Signature <u>Beta Mulenky</u>

Dear Sir:

INFORMATION DISCLOSURE STATEMENT

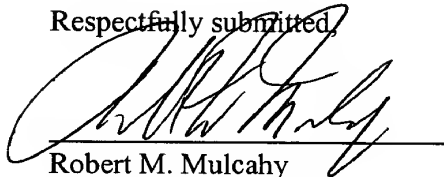
The applicants, and the attorney who signs below on the basis of the information supplied by the inventor and the information in his file, submit herewith patents, publications, or other information of which they are aware, which may be material to the examination of this application and in respect of which there may be a duty to disclose in accordance with 37 C.F.R. 1.56.

While the information submitted in this Information Disclosure Statement may be material pursuant to 37 C.F.R. 1.56, it is not intended to constitute an admission that any patent, publication, or other information referred to therein is prior art for this invention unless specifically designated as such.

In accordance with 37 C.F.R. § 1.97, this Information Disclosure Statement is not to be construed as a representation that a search has been made or that no other possibly material information as defined in 37 C.F.R. § 1.56(a) exists.

The patents and/or publications submitted herewith are set forth on the attached Form PTO-1449.

Respectfully submitted,



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